

- ★ 100% EAS Guaranteed
- ★ Green Device Available
- ★ Super Low Gate Charge
- ★ Excellent CdV/dt effect decline
- ★ Advanced high cell density Trench technology



### Product Summary

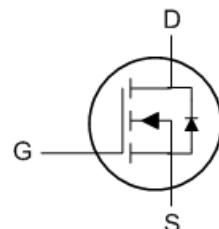
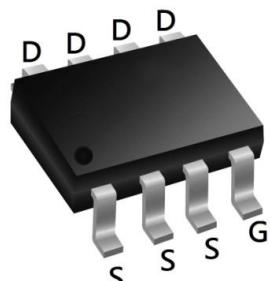
BVDSS	RDS(ON)	ID
40V	9.5mΩ	15A

### Description

The XXW15N04S is the high cell density trenched N-ch MOSFETs, which provide excellent RDS(ON) and gate charge for most of the synchronous buck converter applications.

The XXW15N04S meet the RoHS and Green Product requirement, 100% EAS guaranteed with full function reliability approved.

### SOP8 Pin Configuration



### Absolute Maximum Ratings

Symbol	Parameter	Rating	Units
V <sub>DS</sub>	Drain-Source Voltage	40	V
V <sub>GS</sub>	Gate-Source Voltage	±20	V
I <sub>D</sub> @T <sub>C</sub> =25°C	Continuous Drain Current, V <sub>GS</sub> @ 10V <sup>1</sup>	15	A
I <sub>D</sub> @T <sub>C</sub> =100°C	Continuous Drain Current, V <sub>GS</sub> @ 10V <sup>1</sup>	8	A
I <sub>DM</sub>	Pulsed Drain Current <sup>2</sup>	55	A
EAS	Single Pulse Avalanche Energy <sup>3</sup>	46.1	mJ
I <sub>AS</sub>	Avalanche Current	28	A
P <sub>D</sub> @T <sub>C</sub> =25°C	Total Power Dissipation <sup>4</sup>	3	W
T <sub>STG</sub>	Storage Temperature Range	-55 to 150	°C
T <sub>J</sub>	Operating Junction Temperature Range	-55 to 150	°C

### Thermal Data

Symbol	Parameter	Typ.	Max.	Unit
R <sub>θJA</sub>	Thermal Resistance Junction-ambient (Steady State) <sup>1</sup>	---	62	°C/W
R <sub>θJC</sub>	Thermal Resistance Junction-Case <sup>1</sup>	---	3.8	°C/W

**Electrical Characteristics** ( $T_J=25^\circ\text{C}$  unless otherwise specified)

Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Units
<b>Off Characteristic</b>						
$V_{(BR)DSS}$	Drain-Source Breakdown Voltage	$V_{GS}=0\text{V}$ , $I_D=250\mu\text{A}$	40	-	-	V
$I_{DSS}$	Zero Gate Voltage Drain Current	$V_{DS}=40\text{V}$ , $V_{GS}=0\text{V}$ ,	-	-	1.0	$\mu\text{A}$
$I_{GSS}$	Gate to Body Leakage Current	$V_{DS}=0\text{V}$ , $V_{GS}=\pm 20\text{V}$	-	-	$\pm 100$	nA
<b>On Characteristics</b>						
$V_{GS(\text{th})}$	Gate Threshold Voltage	$V_{DS}=V_{GS}$ , $I_D=250\mu\text{A}$	1.0	1.5	2.5	V
$R_{DS(\text{on})}$ note3	Static Drain-Source on-Resistance	$V_{GS}=10\text{V}$ , $I_D=10\text{A}$	-	9.5	14	$\text{m}\Omega$
		$V_{GS}=4.5\text{V}$ , $I_D=10\text{A}$	-	11.5	16	
<b>Dynamic Characteristics</b>						
$C_{iss}$	Input Capacitance	$V_{DS}=20\text{V}$ , $V_{GS}=0\text{V}$ , $f=1.0\text{MHz}$	-	1639	-	pF
$C_{oss}$	Output Capacitance		-	148	-	pF
$C_{rss}$	Reverse Transfer Capacitance		-	122	-	pF
$Q_g$	Total Gate Charge	$V_{DS}=20\text{V}$ , $I_D=15\text{A}$ , $V_{GS}=4.5\text{V}$	-	16	-	nC
$Q_{gs}$	Gate-Source Charge		-	5	-	nC
$Q_{gd}$	Gate-Drain("Miller") Charge		-	7	-	nC
<b>Switching Characteristics</b>						
$t_{d(on)}$	Turn-on Delay Time	$V_{DS}=20\text{V}$ , $I_D=1\text{A}$ , $R_{GEN}=6.2\Omega$ , $V_{GS}=10\text{V}$	-	10	-	ns
$t_r$	Turn-on Rise Time		-	6	-	ns
$t_{d(off)}$	Turn-off Delay Time		-	50	-	ns
$t_f$	Turn-off Fall Time		-	26	-	ns
<b>Drain-Source Diode Characteristics and Maximum Ratings</b>						
$I_S$	Maximum Continuous Drain to Source Diode Forward Current	-	-	15	-	A
$I_{SM}$	Maximum Pulsed Drain to Source Diode Forward Current	-	-	55	-	A
$V_{SD}$	Drain to Source Diode Forward Voltage	$V_{GS}=0\text{V}$ , $I_S=30\text{A}$	-	-	1.2	V
$trr$	Body Diode Reverse Recovery Time	$I_F=5\text{A}$ , $dI/dt=100\text{A}/\mu\text{s}$	-	13	-	ns
$Qrr$	Body Diode Reverse Recovery Charge		-	7	-	nC

Notes:1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature

2. EAS condition:  $T_J=25^\circ\text{C}$ ,  $V_{GS}=20\text{V}$ ,  $R_G=25\Omega$ ,  $L=0.5\text{mH}$ ,  $I_{AS}=13\text{A}$

3. Pulse Test: Pulse Width $\leq 300\mu\text{s}$ , Duty Cycle $\leq 0.5\%$

### Typical Characteristics

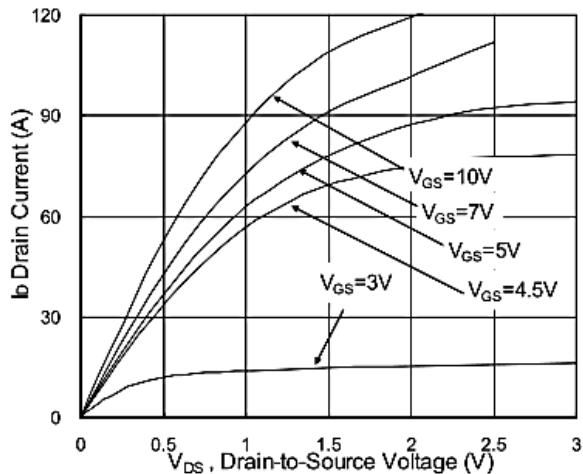


Fig.1 Typical Output Characteristics

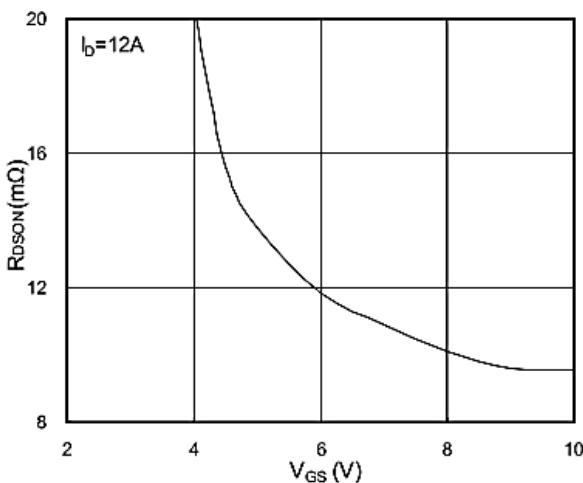


Fig.2 On-Resistance vs. G-S Voltage

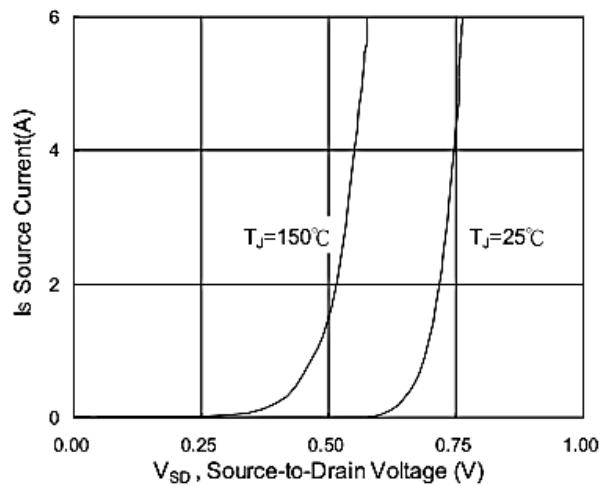


Fig.3 Forward Characteristics of Reverse

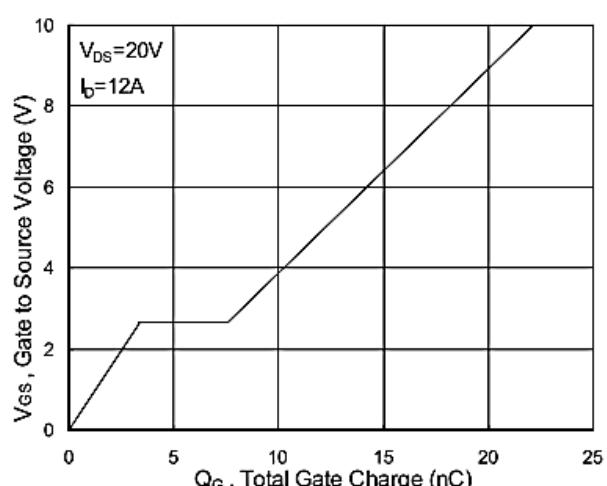


Fig.4 Gate-Charge Characteristics

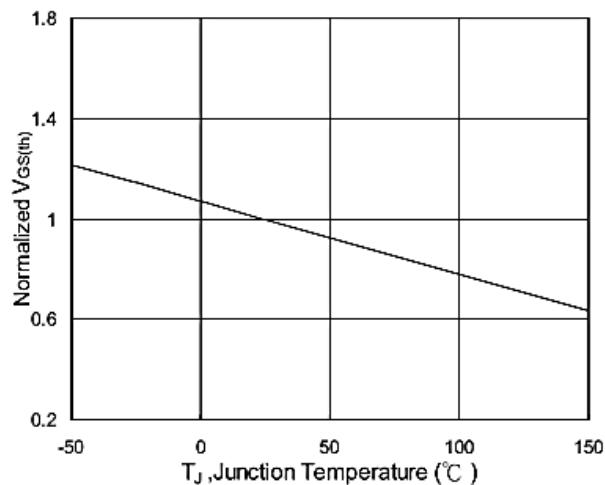


Fig.5  $V_{GS(th)}$  vs.  $T_J$

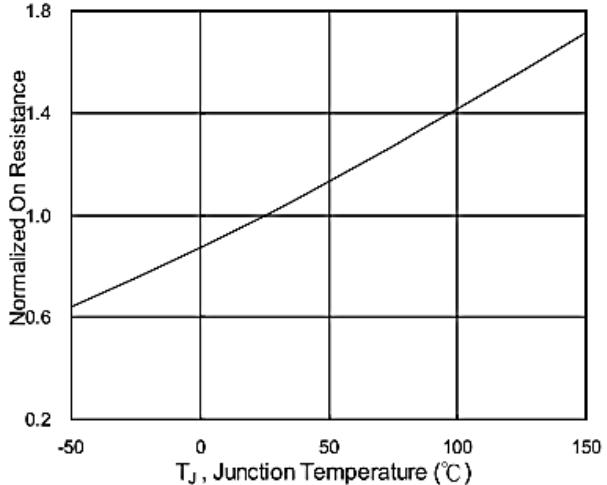
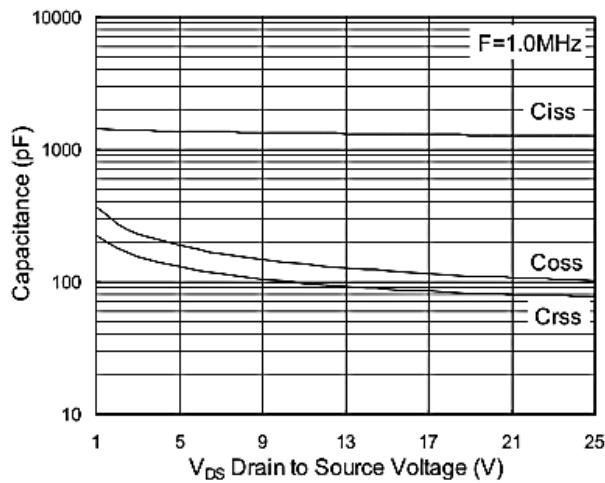
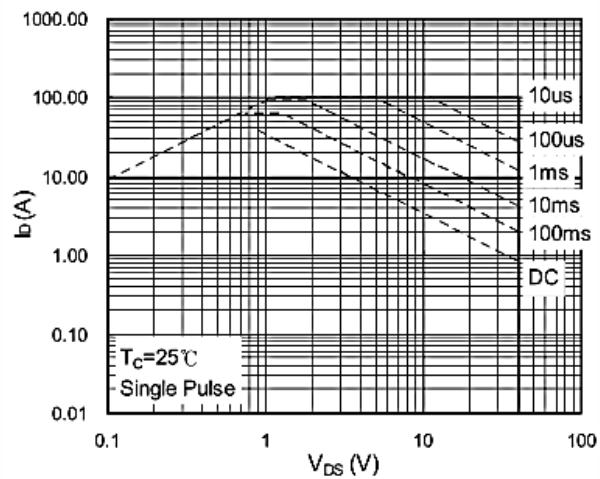
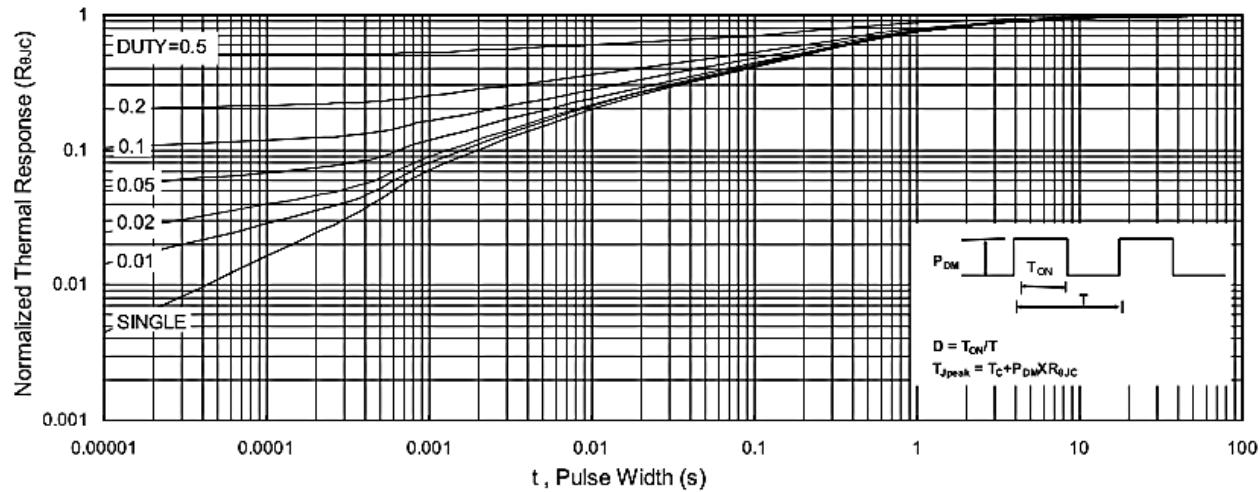
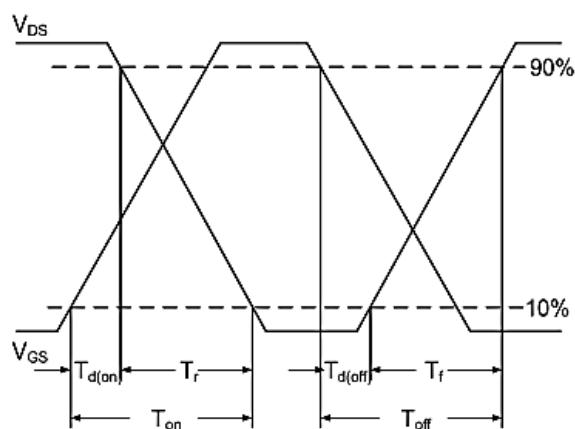
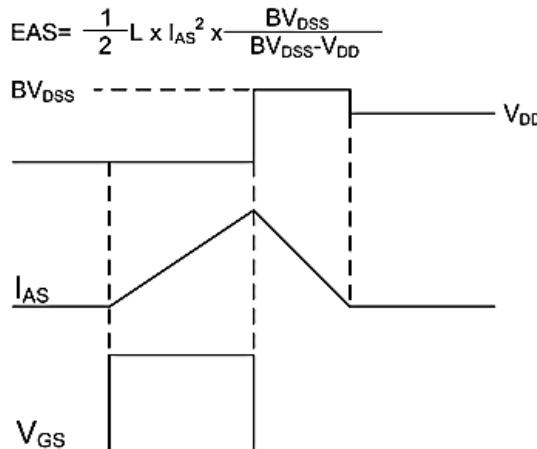


Fig.6 Normalized  $R_{DS(on)}$  vs.  $T_J$

**N-Ch 40V Fast Switching MOSFETs**

**Fig.7 Capacitance**

**Fig.8 Safe Operating Area**

**Fig.9 Normalized Maximum Transient Thermal Impedance**

**Fig.10 Switching Time Waveform**

**Fig.11 Unclamped Inductive Switching Waveform**

## Test Circuit

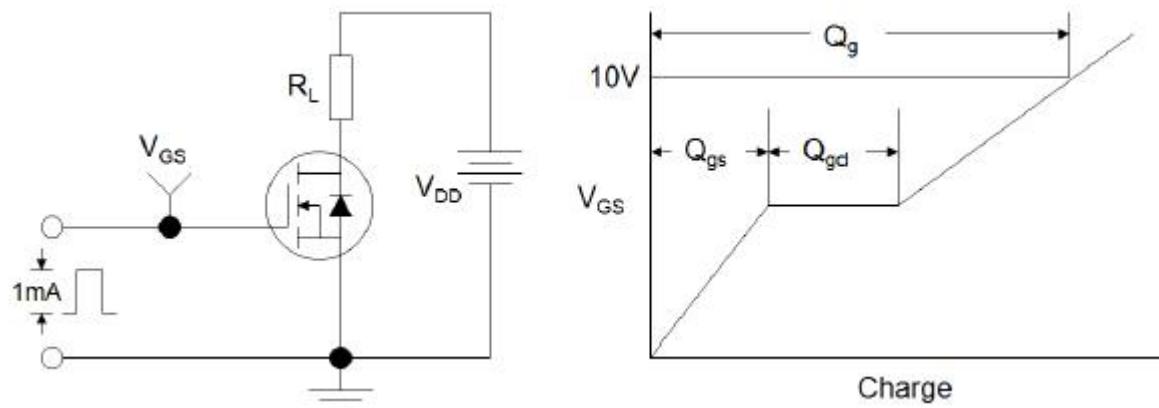


Figure 1: Gate Charge Test Circuit & Waveform

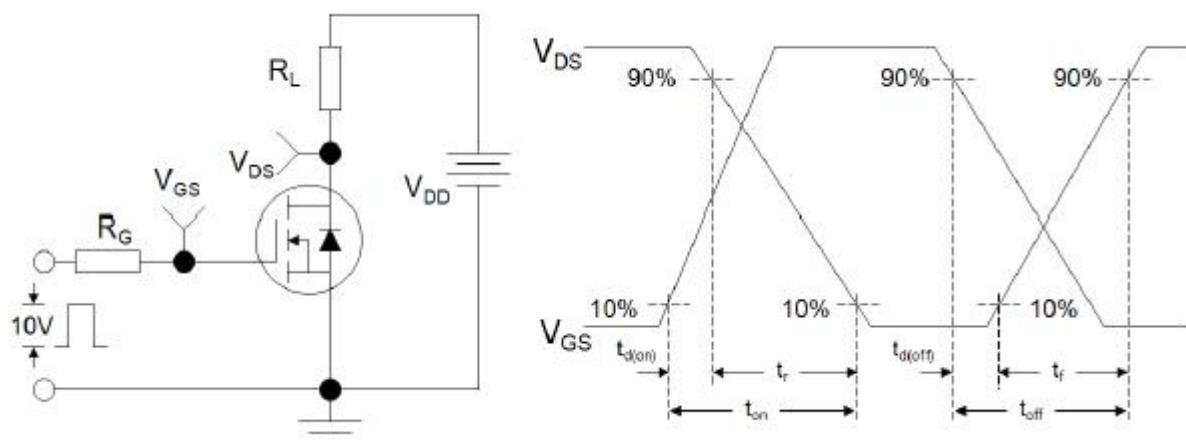


Figure 2: Resistive Switching Test Circuit & Waveforms

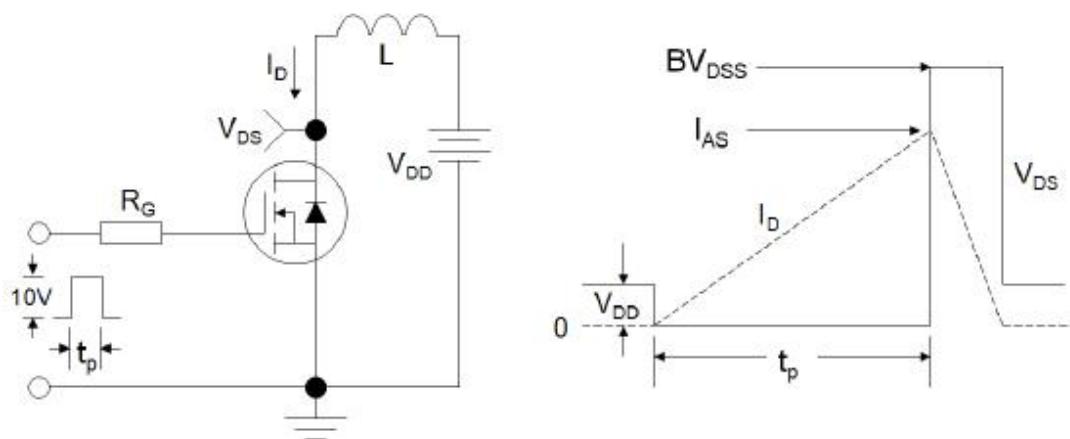
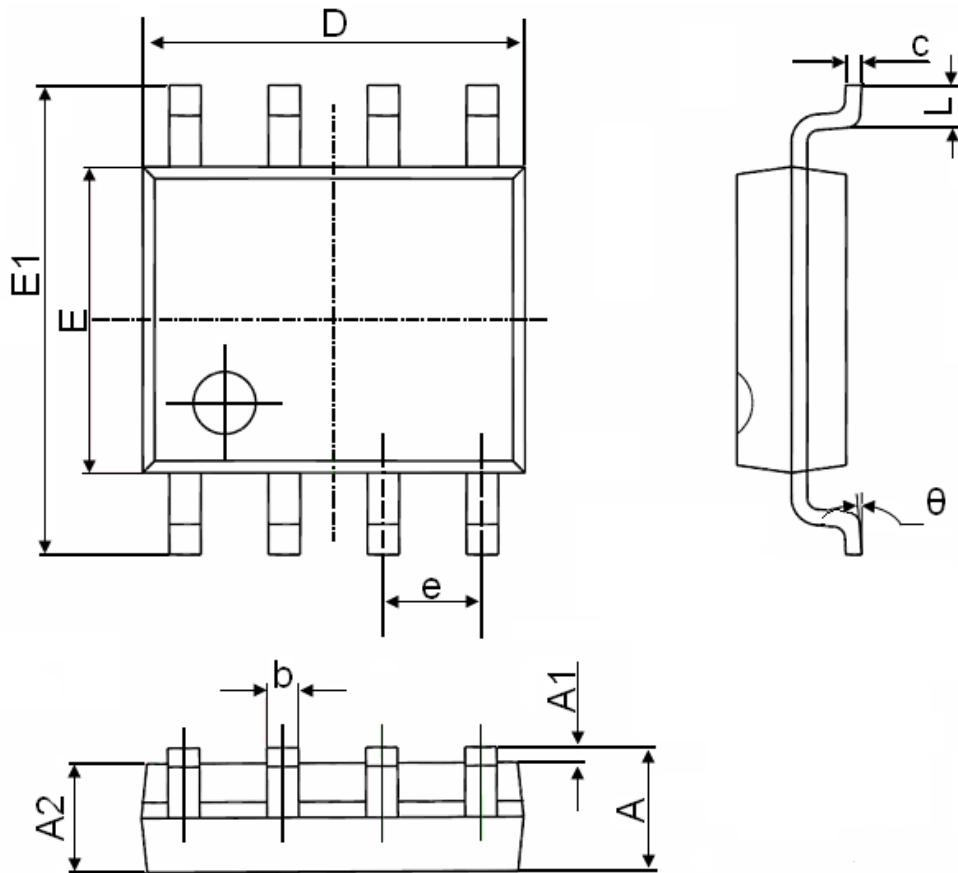


Figure 3: Unclamped Inductive Switching Test Circuit & Waveforms

**SOP-8 Package Information**


Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	1.350	1.750	0.053	0.069
A1	0.100	0.250	0.004	0.010
A2	1.350	1.550	0.053	0.061
b	0.330	0.510	0.013	0.020
c	0.170	0.250	0.006	0.010
D	4.700	5.100	0.185	0.200
E	3.800	4.000	0.150	0.157
E1	5.800	6.200	0.228	0.244
e	1.270(BSC)		0.050(BSC)	
L	0.400	1.270	0.016	0.050
θ	0°	8°	0°	8°